

Date: September 2022
Rev: XIV
No. of Components: Single
Mix Ratio by Weight: N/A
Specific Gravity: 1.80
Pot Life: 28 Days
Shelf Life- Bulk: One year at -40°C
Shelf Life- Syringe: One year at -40°C

Recommended Cure: 150°C / 1 Hour

Minimum Alternative Cure(s):
May not achieve performance properties listed below
 125°C / 2 Hours

NOTES:

- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.

Product Description: EPO-TEK® T6067-3 is a single component thermally conductive epoxy for hybrid die and component attach. It can also be used for semiconductor and high temperature ceramic and vacuum packaging. It is a lower viscosity version of EPO-TEK® T6067.

Typical Properties: Cure condition: 150°C / 1 Hour Different batches, conditions & applications yield differing results.

Data below is not guaranteed. To be used as a guide only, not as a specification. * denotes test on lot acceptance basis

PHYSICAL PROPERTIES:			
* Color (before cure):	White		
* Consistency:	Smooth thixotropic paste		
* Viscosity (23°C) @ 1 rpm:	100,000-150,000	cPs	
Thixotropic Index:	4.1		
* Glass Transition Temp:	≥ 90	°C	(Dynamic Cure: 20-300°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)
Coefficient of Thermal Expansion (CTE):			
	Below Tg:	47	x 10 ⁻⁶ in/in°C
	Above Tg:	167	x 10 ⁻⁶ in/in°C
Shore D Hardness:	89		
Lap Shear @ 23°C:	> 2,000	psi	
Die Shear @ 23°C:	≥ 25	Kg	8,890 psi
Degradation Temp:	403	°C	
Weight Loss:			
	@ 200°C:	0.06	%
	@ 250°C:	0.44	%
	@ 300°C:	0.90	%
Suggested Operating Temperature:	< 300	°C	(Intermittent)
Storage Modulus:	495,349	psi	
Ion Content:	Cl ⁻ :	195 ppm	Na ⁺ : 7 ppm
	NH ₄ ⁺ :	70 ppm	K ⁺ : 14 ppm
* Particle Size:	≤ 20	microns	

ELECTRICAL AND THERMAL PROPERTIES:		
Thermal Conductivity:	1.0	W/mK
Volume Resistivity @ 23°C:	≥ 2 x 10 ¹³	Ohm-cm
Dielectric Constant (1KHz):	3.33	
Dissipation Factor (1KHz):	0.011	

Epoxyes and Adhesives for Demanding Applications™

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EPOXY TECHNOLOGY, INC.

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www.epotek.com

EPO-TEK® T6067-3 Advantages & Suggested Application Notes:

- A high viscosity and thixotropic paste suitable for dispensing, screen printing or manual hand application.
- Performs exceptionally well as a die-attach for small chips such as GaAs, LEDs, diodes and SMD components.
- Capable of resisting 260° C reflow processes, low outgassing hermetic lid seal processes, and organic burn-in up to 150° C/1000 hour storage.
- Capable of JEDEC Level II die attach packaging on die paddles and lead frames.
- Popular for non-electrically conductive die attach capable of bonding to a wide range of substrates including kovar ceramic and BT.
- Available in a higher viscosity version; T6067.
- Can be used as a non-conductive stacking epoxy, in conjunction with E3037, for attaching SMD in hybrid and other packages.

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